Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model **[List multiple models if applicable.]**
HP Synergy 660 Gen10 Compute Module

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	NA
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver	T15/T10
Philps Driver	#2
Flat Head Screw Driver	Medium
Description #4	
Description #5	

3.0 Product Disassembly Process

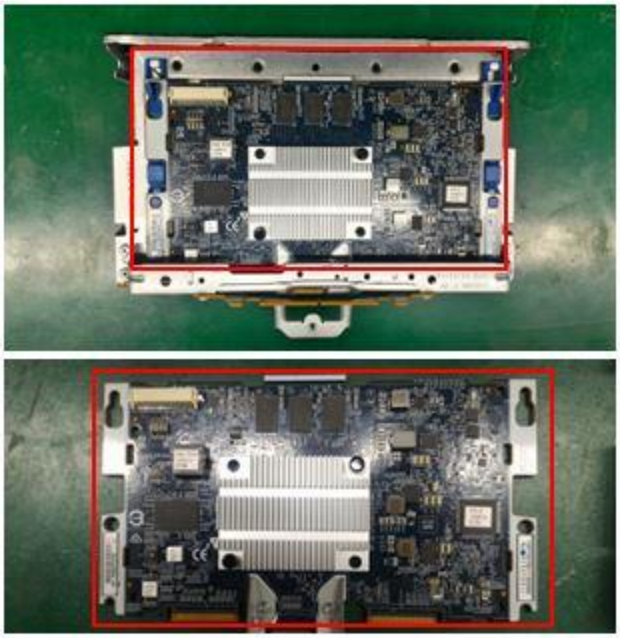
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove FROC(PCBA) with a surface greater than 10 sq cm by Torx Driver and dispose properly
2. Remove HDD backplane(PCBA) with a surface greater than 10 sq cm by Torx Driver and dispose properly
3. System Board Battery -- Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly
4. System Megacell -- Remove the top cover and locate the megacell on the system board. Remove the megacell and dispose of properly.
5. Remove plastics material with a weight greater than 25 grams
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

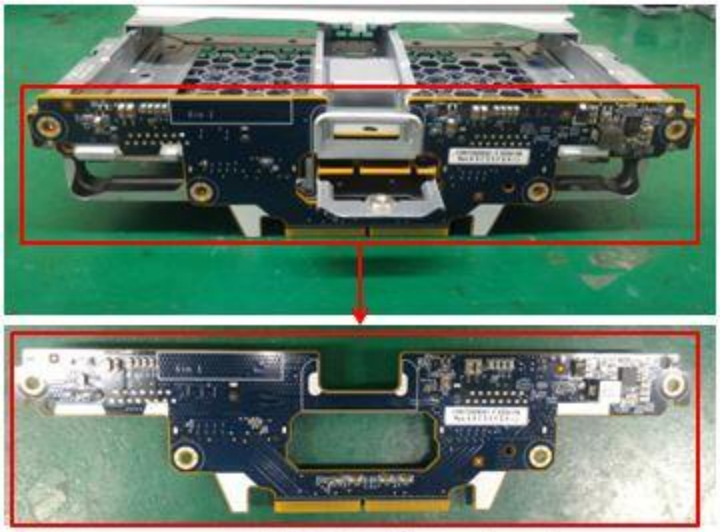
Attachment 1--Location of FROC card.(PCBA)
Attachment 2--Location of HDD backplane.(PCBA)
Attachment 3-- System battery location
Attachment 4-- Location of megacell
Attachment 5—Location of plastics material weight greater than 25g

Attachment 1



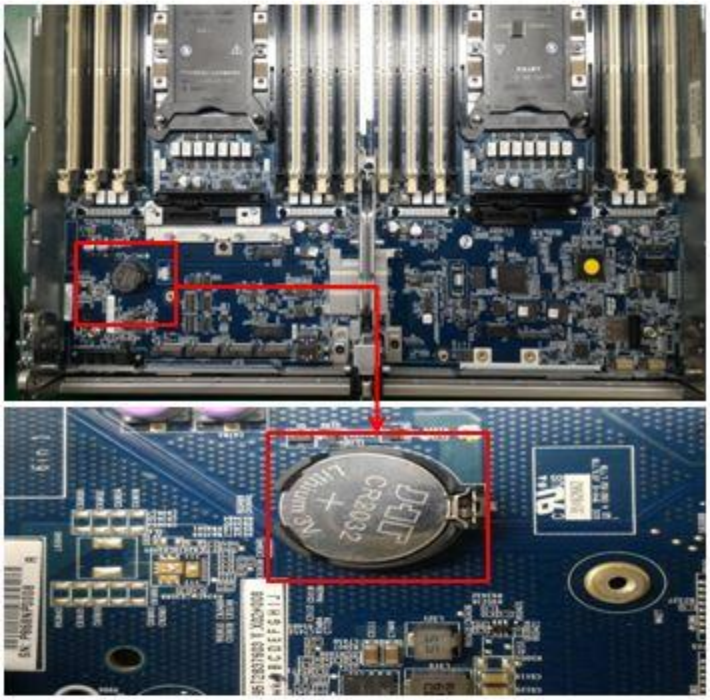
Remove FROC

Attachment 2



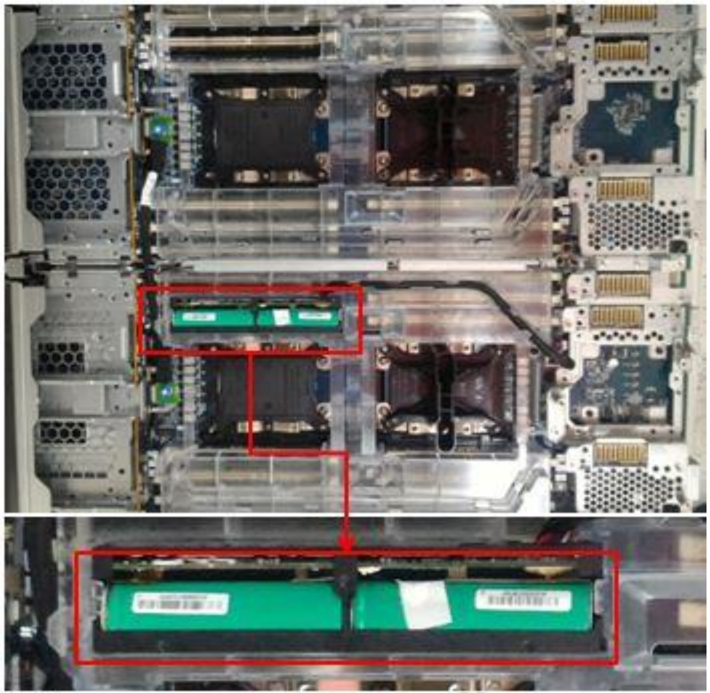
Remove HDD backplane

Attachment 3



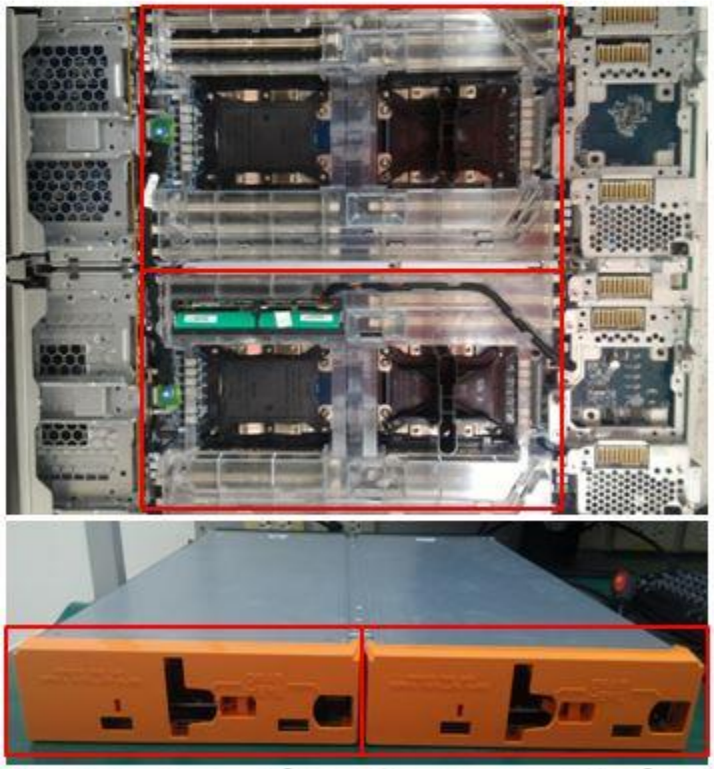
Remove Li battery

Attachment 4



Remove megacell

Attachment 5



Remove plastic material>25g